BGA Heat Sink - High Performance







*Image above is for illustration purpose only

ATS Part#: ATS-59010-C1-R0

62.00 x 52.00 x 13.00 mm BGA Heat Sink - High Performance Device Specific - NXP Description:

Heat Sink Type: NXP

Heat Sink Attachment: maxiGRIP

Equivalent Part Number: N/A

Features & Benefits

- Designed for flip-chip processors such as NXP MPCs
- maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- Comes preassembled with high performance, thermal interface material

Thermal Performance

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	3.2 °C/W	2.6 °C/W	2.1 °C/W	1.9 °C/W	1.7 °C/W	1.5 °C/W	1.4 °C/W
	Ducted Flow	1.8	N/A	N/A	N/A	N/A	N/A	N/A

Product Detail

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	TIM	Finish
	62.00 mm	52.00 mm	13.00 mm	52 mm	3M8815	BLACK-ANODIZED
	 Dimensio Thermal applicatio ATS rese performa ATS certi Optional 	performance data a on. erves the right to up nce. ifies that this heat s maxiGRIP™ Install	component size. Theight from the both tre provided for reference date or change its prink assembly is Rolation/Removal Tool custom options avai	oroducts without no HS-6 and REACH of I Set P/N: MGT170	performance tice to impro-	may vary by
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